TO-252



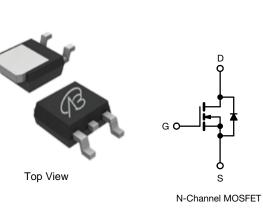
N-Channel 650V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.240		

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)





APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage	V _{DS}	650	v		
Gate-source voltage	V _{GS}	± 30			
Continuous drain surrant $(T = 150 ^{\circ}\text{C})$	V_{GS} at 10 V $T_C = 25 \degree C$ $T_C = 100 \degree C$	1	15		
Continuous drain current ($T_J = 150 \ ^{\circ}C$)	V_{GS} at 10 V $T_C = 100 \text{ °C}$	I _D	9	А	
Pulsed drain current ^a	I _{DM}	45	1		
Linear derating factor		1.7	W/°C		
Single pulse avalanche energy ^b	E _{AS}	350	mJ		
Maximum power dissipation	PD	180	W		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C	d\//dt	50	V/ns	
Reverse diode dV/dt ^d		dV/dt	5.1	v/ns	
Soldering recommendations (peak temperature) ^c	For 10 s		260	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 $\Omega,\,I_{AS}$ = 7 A
- c. 1.6 mm from case
- d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C

VBE165R15S



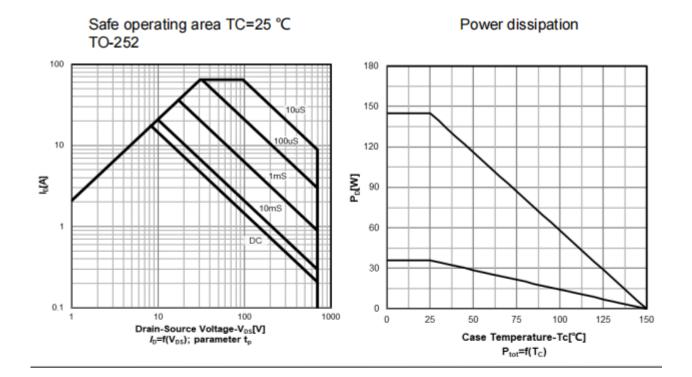
THERMAL RESISTANCE RAT	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	- 62			00.00			
Maximum junction-to-case (drain)	R _{thJC}	- 0.85			°C/W			
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static	•				•	•	•	
Drain-source breakdown voltage	V _{DS}	V _{GS} =	0 V, I _D = 2	250 μA	650	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	$I_D = 1 \text{ mA}$	-	1.08	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2.0	-	4.0	V
Osta asuma laskana		$V_{GS} = \pm 20 V$		-	-	± 100	nA	
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
		V _{DS} =	= 650 V, V _C	_{is} = 0 V	-	-	1	
Zero gate voltage drain current	IDSS	$V_{DS} = 520 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$		-	-	10	μA	
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = 10 V$	l	_D =5A	-	0.240	-	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D =	= 12 A	-	8.7	-	S
Dynamic								
Input capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	1900	-	pF	
Output capacitance	C _{oss}			-	51	-		
Reverse transfer capacitance	C _{rss}			-	12	-		
Effective output capacitance, energy related ^a	C _{o(er)}	$V_{DS} = 0 V$ to 480 V, $V_{GS} = 0 V$		-	49	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	205	-		
Total gate charge	Qg				-	25	-	
Gate-source charge	Q _{gs}	V _{GS} = 10 V I _D = 12 A, V _{DS} = 480 V		-	8	-	nC	
Gate-drain charge	Q _{gd}				-	10	-	
Turn-on delay time	t _{d(on)}				-	12	24	
Rise time	t _r	V _{DD} =	- 480 V In	= 12 A	-	14	23	
Turn-off delay time	t _{d(off)}	$V_{DD} = 480 \text{ V}, \text{ I}_{D} = 12 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	61	110	ns	
Fall time	t _f]			-	16	-	
Gate input resistance	R _g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω	
Drain-Source Body Diode Characteristi	cs							
Continuous source-drain diode current	١ _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15		
Pulsed diode forward current	I _{SM}			-	-	45	A	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 12 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}				-	45	90	ns
Reverse recovery charge	Q _{rr}	T _J = 25 °C, $I_F = I_S = 12 \text{ A}$, dl/dt = 100 A/µs, $V_R = 25 \text{ V}$		-	6.4	12.8	μC	
Reverse recovery current	I _{RRM}			-	27	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}

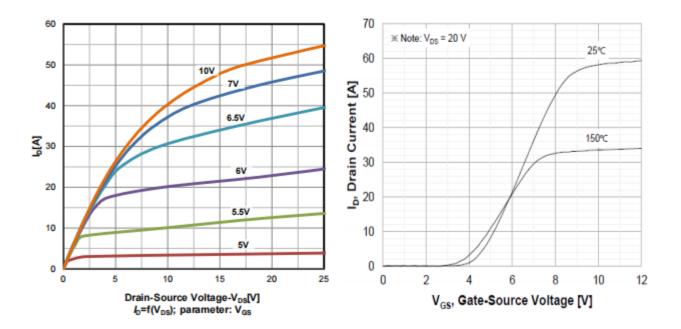


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Typ. output characteristics $T_i=25 \ ^{\circ}C$

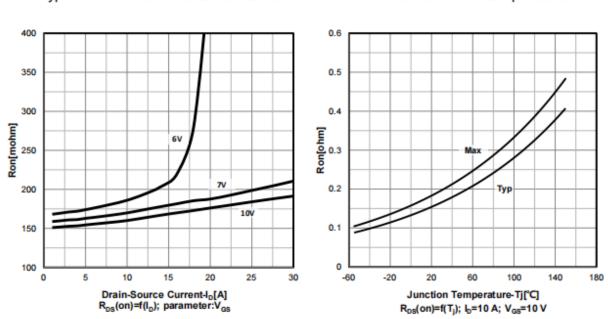
Transfer characteristics



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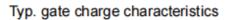


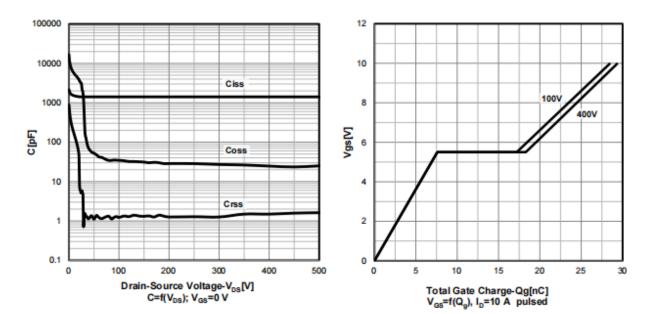


Typ. drain-source on-state resistance

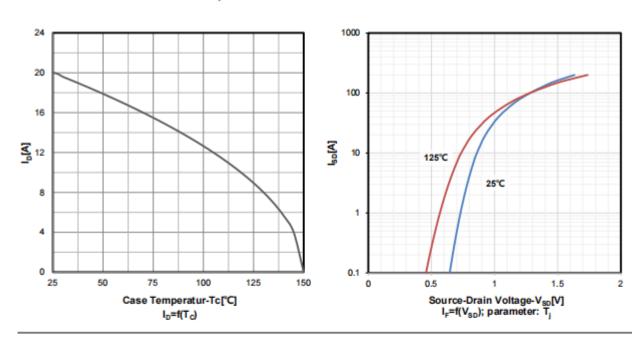
On-resistance vs temperature

Typ. capacitances







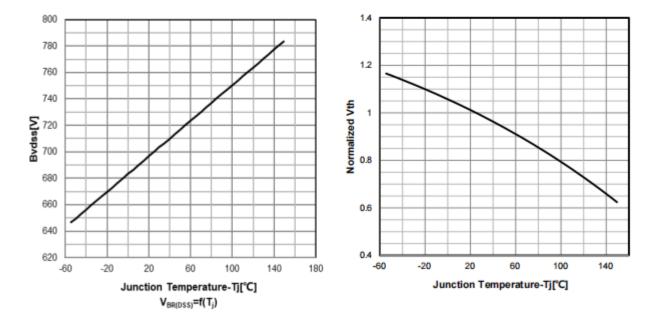


Drain current vs temperature

Forward characteristics of reverse diode

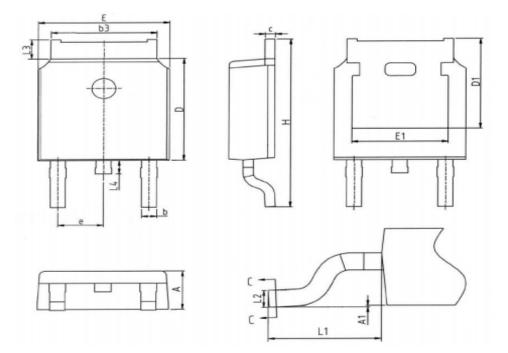
Drain-source breakdown voltage

Normalized VGS(th) characteristics





Package Outline : TO 252



COMMON DIMENSIONS

SYMBOL	UNIT(mm)			
SIMBOL	MIN	NOM	MAX	
A	2.20	2.30	2.40	
A1	0.00	-	0.127	
b	0.66	0.78	0.90	
b3	5.16	5.31	5.46	
с	0.43	0.53	0.63	
D	5.98	6.10	6.22	
D1	5.30REF			
E	6.40	6.60	6.75	
E1	4.63	-	-	
е	2.286BSC			
H	9.40	10.10	10.50	
L1	2.90REF			
L2	0.51BSC			
L3	0.88	1.08	1.28	
L4	0.50	0.80	1.00	



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